IPC ASSOCIATION CONNECTELECTRONICS INDUSTRI	Material Composi © Copyright 2005. IPC, international and Pan-A	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.							
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					on		
upplier Infor								,		٦			
Company name* Company unique ID				Ţ	Unique ID Authority				Response Date*				
nsemi									2024-04-25				
Contact Name Title - Contact					I	Phone - Contact* Email - Contact*							
Product-Env-Ste	wards	Product	act Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title -			- Representative			Phone - Representative*			Email - Representative*				
Product-Env-Stewards Product Enviro Compliance			Enviro Compliance		1	NA Product-Env-Stewards@onsemi.com					m		
Reque	Requester Item Number Mfr Iten		Number Mfr Item Name			Effective Date	Version	N	Manufacturing Site	We	ight*	UOM	Unit Type
		AR0239ATSH002 A0-DPBR	UE 2MP 1/3 CIS SO)		2024-04-25		Т	`A1	196	.1	mg	Each
Ianufacturin	g Proccess Information	n											
Termin	Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 M			J-STD-020 MS	L Rating	Peak Proc	ess Body T	emperatur	e Max Time at Peak	Temperature	Numbe	er of Reflow Cyc	les
SnAgCu CU		CU Alloy	TU Alloy 3			260	C 30		seconds	3			
omments													
FTENTION: M	SL 3 Rated item requires B	ake and Dry Pack	after electrical test)										
or more informa	ation regarding material cor	nposition please re	er to page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	46.097	mg		Misc.	proprietary data		0.1752	mg
			Supplier	Silicon (Si)	7440-21-3		45.4655	mg
			Supplier	Aluminum (Al)	7429-90-5		0.4564	mg
Die Attach	2.811	mg		Bismaleimide Monomer	proprietary data		1.0822	mg
			Supplier	POLY(ETHYLENE GLYCOL) PHENYL ETHER ACRYLATE	56641-05-5		0.0141	mg
			Supplier	2,2-Bis(4-hydroxyphenyl)propane- epichlorohydrin copolymer acrylate	55818-57-0		0.2811	mg
			Supplier	Bis(4-tert-butylcyclohexyl) peroxydicarbonate	15520-11-3		0.0141	mg
			Supplier	2,2-dimethyl-1,3-propanediyl dimethacrylate	1985-51-9		0.2811	mg
			Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.2811	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.0141	mg
			Supplier	Other Additive Agents	Proprietary Data		0.5622	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.2811	mg
Ероху	1.438	mg	Supplier	Imidazole Addition	68490-66-4		0.4314	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.1438	mg
			Supplier	Zirconium Dioxide (ZrO2)	1314-23-4		0.1438	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.1438	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.5752	mg
Imaging Lens	28.822	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.5169	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.5169	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.5169	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.1519	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.5169	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.5169	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		21.0856	mg
Mold Compound	42.869	mg		Epoxy resin	proprietary data		10.6315	mg
			Supplier	Other Additive Agents	Proprietary Data		1.3718	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		4.2869	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.2927	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.2861	mg

Solder Ball	35.356	mg	Supplier	Silver (Ag)	7440-22-4	1.0607	mg
			Supplier	Tin (Sn)	7440-31-5	34.1185	mg
			Supplier	Copper (Cu)	7440-50-8	0.1768	mg
Solder Mask	4.15	mg		Epoxy resin	proprietary data	0.498	mg
			Supplier	Acrylate	Proprietary Data	1.5853	mg
			Supplier	Talc	14807-96-6	0.1121	mg
			Supplier	Miscellaneous	Trade Secret	0.1535	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	1.8011	mg
Substrate Copper Foil	3.194	mg	Supplier	Copper (Cu)	7440-50-8	3.194	mg
Substrate - Core Material	15.866	mg		Epoxy resin	proprietary data	3.4382	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3	12.4278	mg
Substrate Plating-Au	0.275	mg	Supplier	Gold (Au)	7440-57-5	0.275	mg
Substrate Plating-Cu	14.28	mg	Supplier	Copper (Cu)	7440-50-8	14.28	mg
Substrate Plating-Ni	0.66	mg	В	Nickel (Ni)	7440-02-0	0.66	mg
Wire Bond - Au	0.282	mg	Supplier	Gold (Au)	7440-57-5	0.282	mg